

LCD

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Development of LCD-Oriented Impact Analysis System

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Key Words : Modeling(), TFT-LCD(), Pre-Processor(), Impact Analysis()

Abstract

Impact analysis of TFT-LCD module is very complicated because the structure is assisted with thin, small and non-uniform geometry. Especially, finite element modeling is more difficult and need time-consuming efforts. In this study, we developed LCD Impact Analysis System (LIAS) for the purpose of reducing the analysis time without accuracy reduction. This system contains pre-meshing data, material database, shock condition, auto-reporting etc. PATRAN and DYNA3D is used for meshing and solving. Previously, we performed impact test and reviewed the accuracy of analysis results. Simply we can control design parameters, the procedure such as meshing, running and reporting which are partially auto-prepared. By adopting proposed system, it is expected to achieve efficient impact analysis of LCD module.

DYNA3D

1.

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TFT-LCD(Thin Film Transistored Liquid Crystal Display)

(2)

TFT-LCD

(Back Light Unit)

가

가

가

(1)

가

가

가가 가

(LCD Impact Analysis System,

LIAS)

(4)

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AMLCD

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AMLCD

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가가 가

2. LIAS

2.1

가

Fig.1
 Top Chassis(TC), (Panel),
 (Back Light Unit, BLU)
 BLU 가

가

Δt

(3)

$$\Delta t = l_{min} / vL \quad (1)$$

l_{min} , v

BLU

가

가,

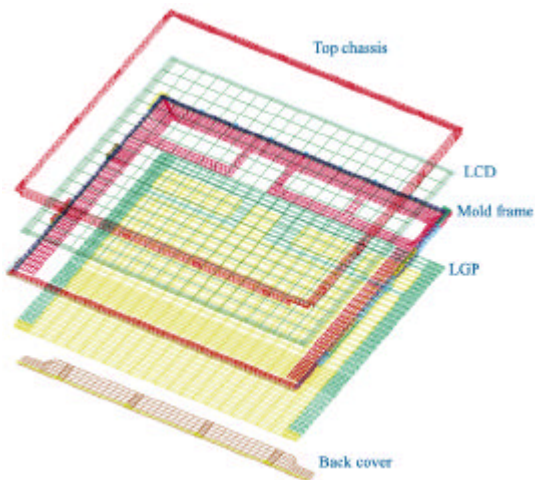


Fig. 1 Main structure of TFT-LCD module

2.2 LIAS

LIAS

DYNA3D

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Fig.2

PATRAN

3. LIAS

3.1 LIAS

Fig.3 LIAS

GUI

PATRAN

Open GL

가

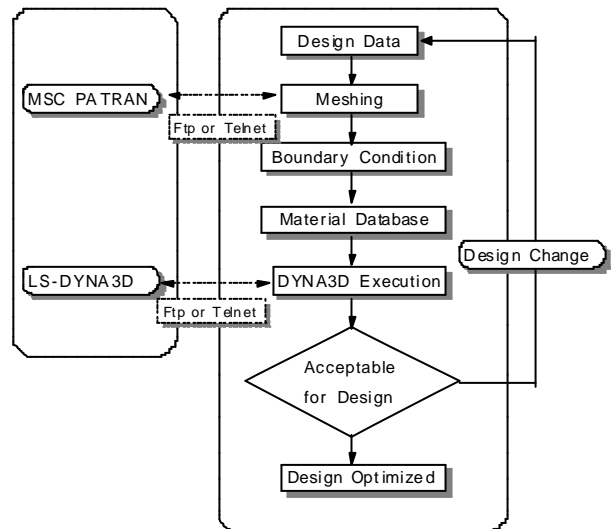


Fig. 2 Main procedure of LIAS system

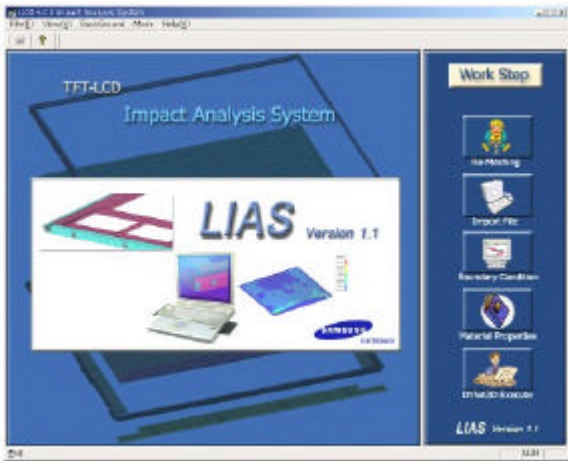


Fig. 3 Main stage of LIAS system

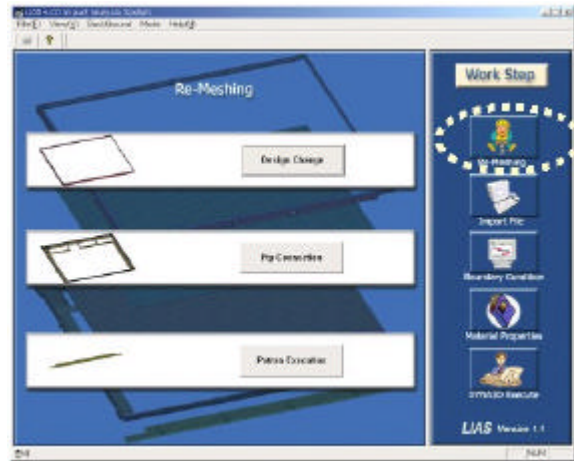


Fig. 4 Meshing module of LIAS system

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3.2 LIAS

3.2.1 (Re-meshing module)

Fig.4

(Top chassis), (mold frame), (back cover)

3.2.2 (Import File Module)

Fig.5

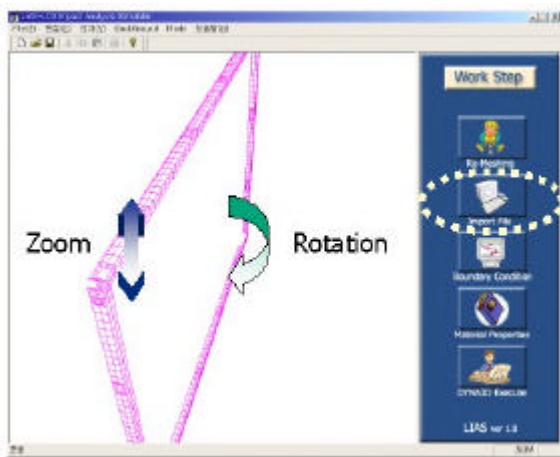


Fig. 5 Import file module of LIAS system

LS-DYNA

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3.2.3 (Boundary Condition Module)

Fig.6

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3.2.4 (Material Property Module)

Fig.7

3.2.5 LS-DYNA Execute Module

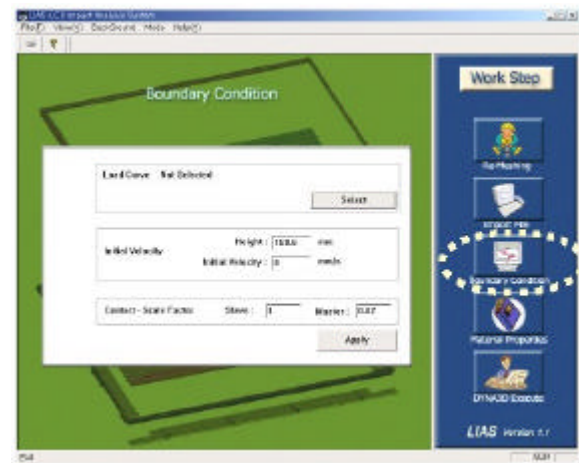


Fig. 6 Boundary condition module of LIAS system

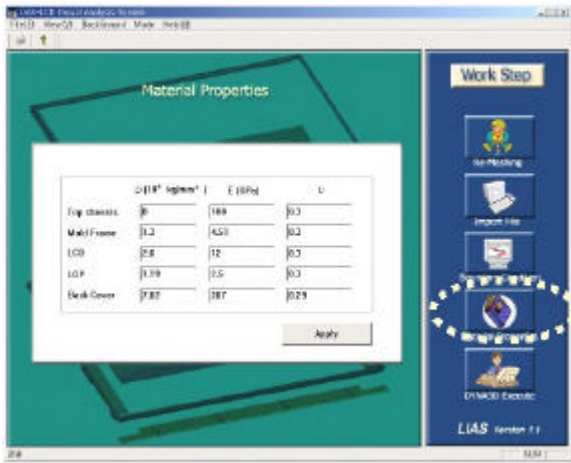


Fig. 7 Material property module of LIAS system

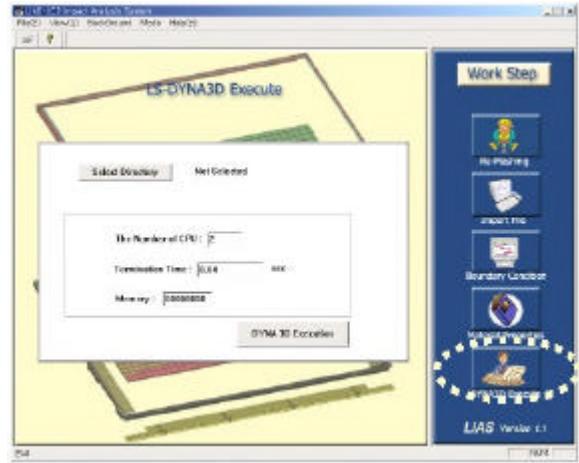


Fig. 8 LS-DYNA Execute Module of LIAS system

Fig.8

, CPU

4. LIAS

4.1

LIAS

LIAS

Fig.9

Fig.10

TC

, LIAS

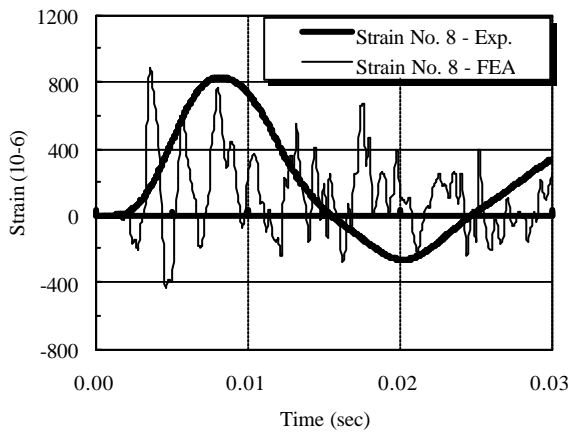


Fig. 9 Time history of strain (x) for the middle part of LCD panel

4.2

, LIAS

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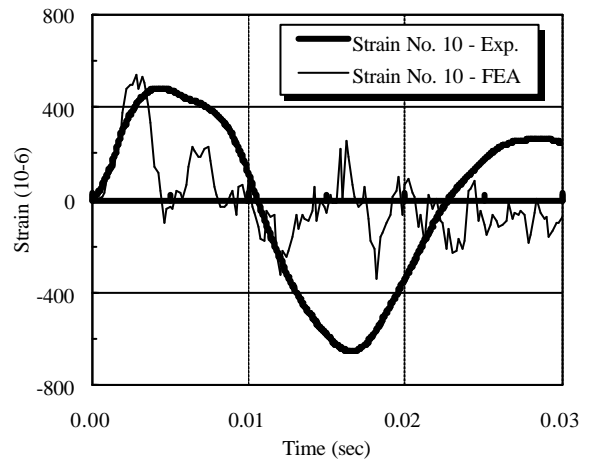


Fig. 10 Time history of strain (y) for the middle part of top-chassis

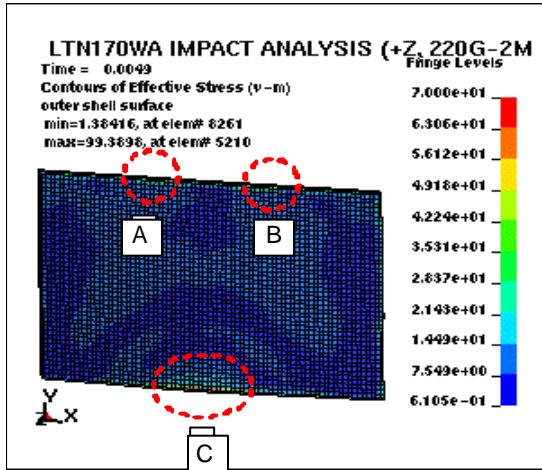


Fig. 11 Von-Mises stress distribution of LCD panel

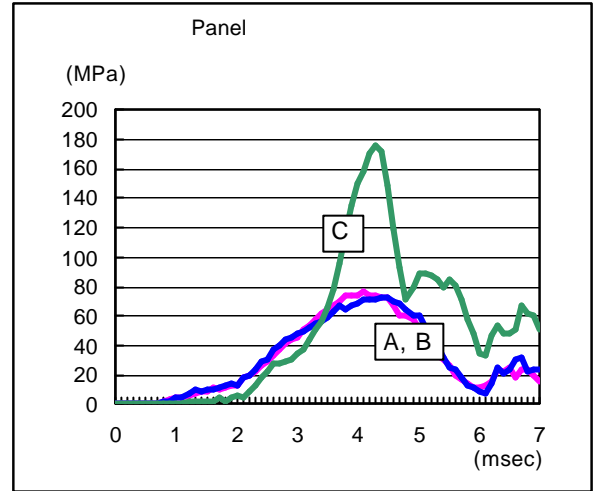


Fig. 12 Time history of Von-Mises stress on the weak points of LCD panel

3 CAD
 1 , 2
 1 가
 가
 4.2.1 가
 Fig.11 Fig.12

C
 , (Beading) 가
 4.2.2 가
 Fig.13 Fig.14

A, B 가 C

, 가 가
 3.5msec 가

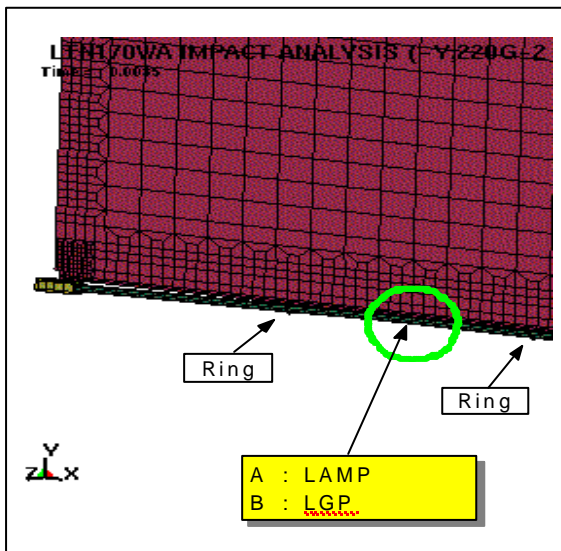


Fig. 13 Deformed shape between lamp and LGP

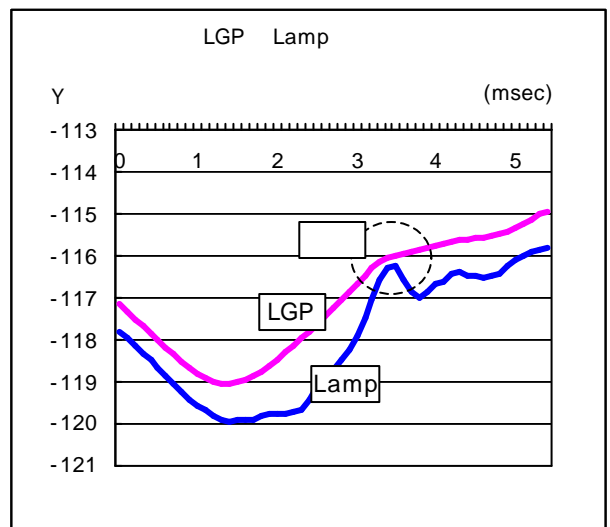


Fig. 14 Time history of deformation between lamp and LGP

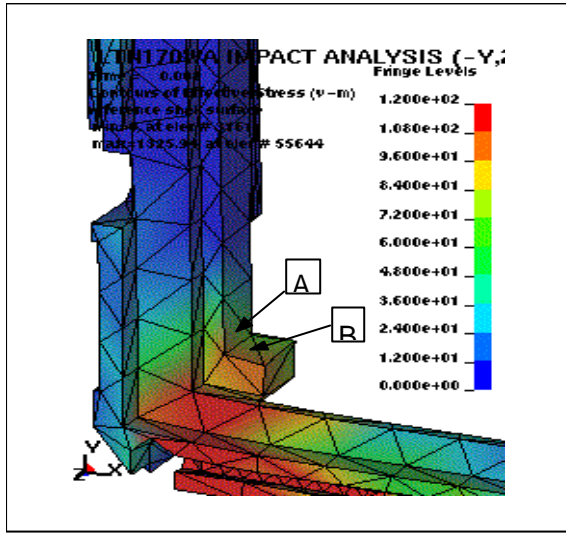


Fig. 15 Von-Mises stress distribution on the weak points of mold frame

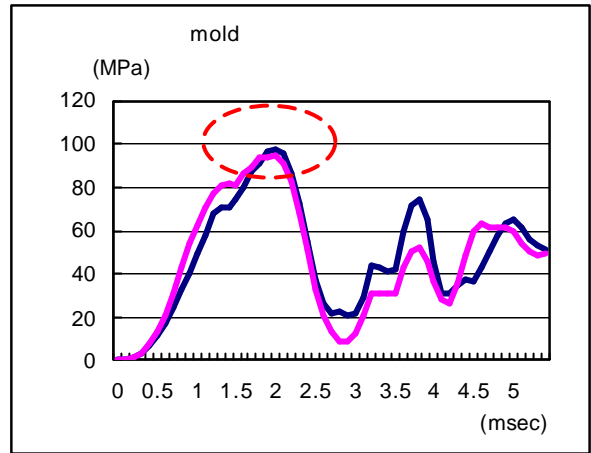


Fig. 16 Time history of Von-Mises stress on the weak points of mold frame

4.2.3

Fig. 15

Fig. 16

(-Y)

5. LIAS

TV

.CAE

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LIAS

CAD

CAE (LIAS)

CAD

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